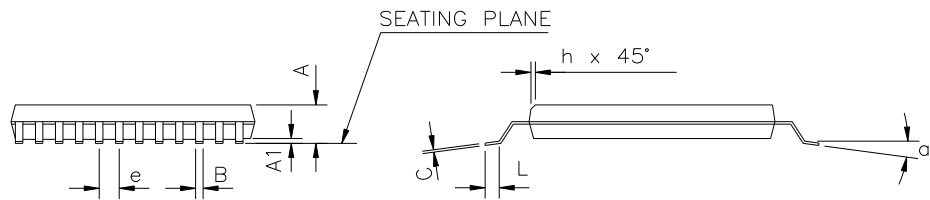
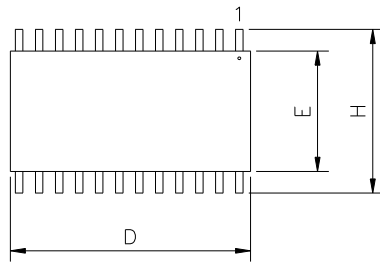


150 MIL QSOP
QUARTER SIZE OUTLINE PACKAGE(QSOP)

PACKAGE INFORMATION

NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-137AB		MO-137AD		MO-137AE		MO-137AF	
TYPE	16 LEAD		20 LEAD		24 LEAD		28 LEAD	
SYMBOL	Min	Max	Min	Max	Min	Max	Min	Max
A	0.060	0.068	0.060	0.068	0.060	0.068	0.060	0.068
A1	0.004	0.008	0.004	0.008	0.004	0.008	0.004	0.008
B	0.009	0.012	0.009	0.012	0.009	0.012	0.009	0.012
C	0.007	0.010	0.007	0.010	0.007	0.010	0.007	0.010
D	0.188	0.197	0.337	0.344	0.337	0.344	0.386	0.394
E	0.150	0.157	0.150	0.157	0.150	0.157	0.150	0.157
e	0.025 BSC		0.025 BSC		0.025 BSC		0.025 BSC	
H	0.230	0.244	0.230	0.244	0.230	0.244	0.230	0.244
h	0.010	0.016	0.010	0.016	0.010	0.016	0.010	0.016
L	0.016	0.035	0.016	0.035	0.016	0.035	0.016	0.035
α°	0°	8°	0°	8°	0°	8°	0°	8°

PREPARED BY	NK	REF. NO. DIM-QSOP-01	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA		
CHECKED BY	SP		1			
APPROVED BY	NJC		DATE 01.07.01			